

Application No. 10/717,355
Reply to Office Action of December 2, 2004

Amendments to the Abstract:

On page 21 of the specification, amend paragraph [00044] as follows:

[00044] A microelectronic structure ~~that~~ includes a semi-conducting substrate including circuits formed therein and a top surface, and at least one conductive bump situated on the top surface providing electrical communication to the circuits[[,] ~~the~~ The at least one conductive bump has a sidewall formed of an electrically insulating material. The portions of the conductive bump other than the sidewall is a unitary structure. The top surface of the conductive bump is uncovered and directly exposed to its surroundings.